



512K X 8 BIT LOW POWER CMOS SRAM

FEATURES

- Access time : 55 ns
- Low power consumption:
Operating current : 30/20mA (TYP.)
Standby current : 4 μA (TYP.) C-version
- Single 2.7V ~ 5.5V power supply
- Fully Compatible with all Competitors 5V product
- Fully Compatible with all Competitors 3.3V product

- Fully static operation
- Tri-state output
- Data retention voltage : 2.0V (MIN.)
- All products ROHS Compliant
- Package 32-pin 450 mil SOP
 32-pin 8mm x 20mm TSOP-I
 32-pin 600 mil P-DIP
 32-pin 8mm x 13.4mm sTSOP
 *36-ball 6mm x 8mm TFBGA
 *

Coming
Soon!

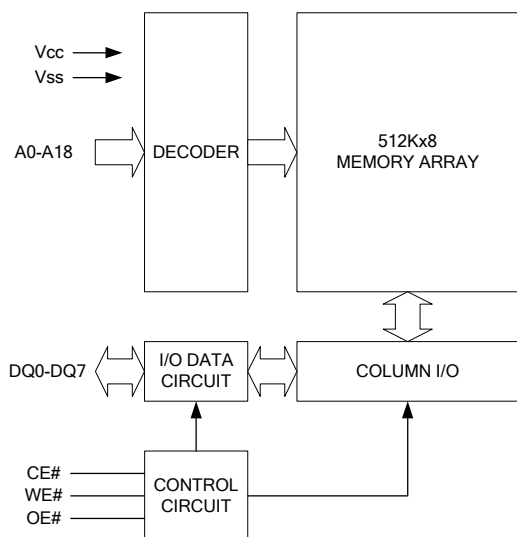
GENERAL DESCRIPTION

The AS6C4008 is a 4,194,304-bit low power CMOS static random access memory organized as 524,288 words by 8 bits. It is fabricated using very high performance, high reliability CMOS technology. Its standby current is stable within the range of operating temperature.

The AS6C4008 is well designed for very low power system applications, and particularly well suited for battery back-up non-volatile memory application.

The AS6C4008 operates from a single power supply of 2.7V ~ 5.5V

FUNCTIONAL BLOCK DIAGRAM



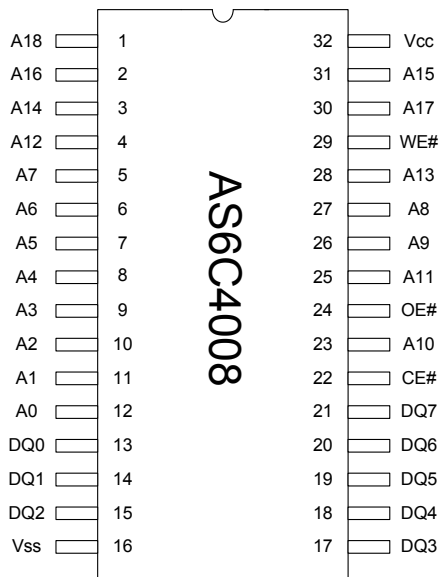
PIN DESCRIPTION**

SYMBOL	DESCRIPTION
A0 - A18	Address Inputs
DQ0 - DQ7	Data Inputs/Outputs
CE#	Chip Enable Inputs
WE#	Write Enable Input
OE#	Output Enable Input
Vcc	Power Supply
Vss	Ground
NC	No Connection

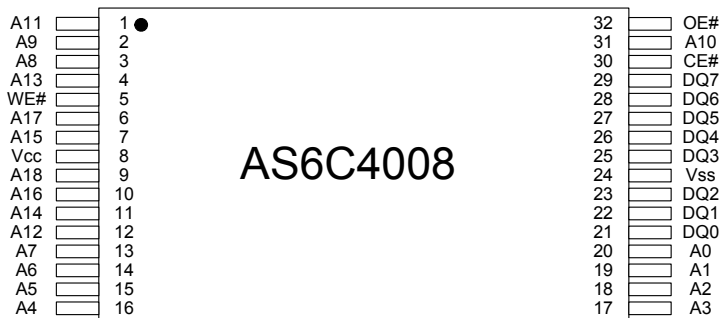


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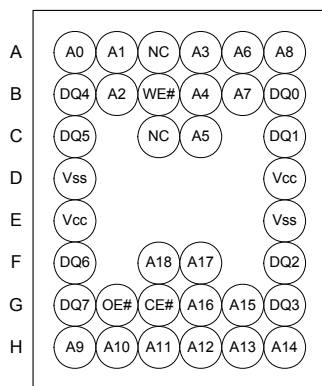
PIN CONFIGURATION



SOP/P-DIP



TSOP-I/TSOP



TFBGA



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ABSOLUTE MAXIMUM RATINGS*

PARAMETER	SYMBOL	RATING	UNIT
Terminal Voltage with Respect to V _{SS}	V _{TERM}	-0.5 to 6.5	V
Operating Temperature	T _A	0 to 70(C grade)	°C
		-40 to 85(I grade)	
Storage Temperature	T _{STG}	-65 to 150	°C
Power Dissipation	P _D	1	W
DC Output Current	I _{OUT}	50	mA
Soldering Temperature (under 10 sec)	T _{SOLDER}	260	°C

*Stresses greater than those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to the absolute maximum rating conditions for extended period may affect device reliability.

TRUTH TABLE

MODE	CE#	OE#	WE#	I/O OPERATION	SUPPLY CURRENT
Standby	H	X	X	High-Z	I _{SB1}
Output Disable	L	H	H	High-Z	I _{CC} , I _{CC1}
Read	L	L	H	D _{OUT}	I _{CC} , I _{CC1}
Write	L	X	L	D _{IN}	I _{CC} , I _{CC1}

Note: H = V_{IH}, L = V_{IL}, X = Don't care.

DC ELECTRICAL CHARACTERISTICS

PARAMETER	SYMBOL	TEST CONDITION	MIN.	TYP. ³	MAX.	UNIT	
Supply Voltage	V _{CC}		2.7	3.0	5.5	V	
Input High Voltage	V _{IH} ¹		0.7* V _{CC}	-	V _{CC} +0.3	V	
Input Low Voltage	V _{IL} ¹		-0.2	-	0.6	V	
Input Leakage Current	I _{LI}	V _{CC} ≥ V _{IN} ≥ V _{SS}	-1	-	1	μA	
Output Leakage Current	I _{LO}	V _{CC} ≥ V _{OUT} ≥ V _{SS} , Output Disabled	-1	-	1	μA	
Output High Voltage	V _{OH}	I _{OH} = -1mA	2.4	-	-	V	
Output Low Voltage	V _{OL}	I _{OL} = 2mA	-	-	0.4	V	
Average Operating Power supply Current	I _{CC}	Cycle time = Min. CE# = 0.2V, I _{I/O} = 0mA other pins at 0.2V or V _{CC} - 0.2V	-55	-	30	60	mA
	I _{CC1}	Cycle time = 1μs CE# = 0.2V, I _{I/O} = 0mA other pins at 0.2V or V _{CC} - 0.2V	-	4	10	mA	
Standby Power Supply Current	I _{SB1}	CE# ≥ V _{CC} - 0.2V	*C	-	4	50 ⁴	μA
			*I	-	4	50 ⁴	μA

Notes: 1. V_{IH}(max) = V_{CC} + 3.0V for pulse width less than 10ns. V_{IL}(min) = V_{SS} - 3.0V for pulse width less than 10ns.

2. Over/Undershoot specifications are characterized, not 100% tested.

3. Typical values are included for reference only and are not guaranteed or tested.

Typical values are measured at V_{CC} = V_{CC}(TYP.) and T_A = 25°C

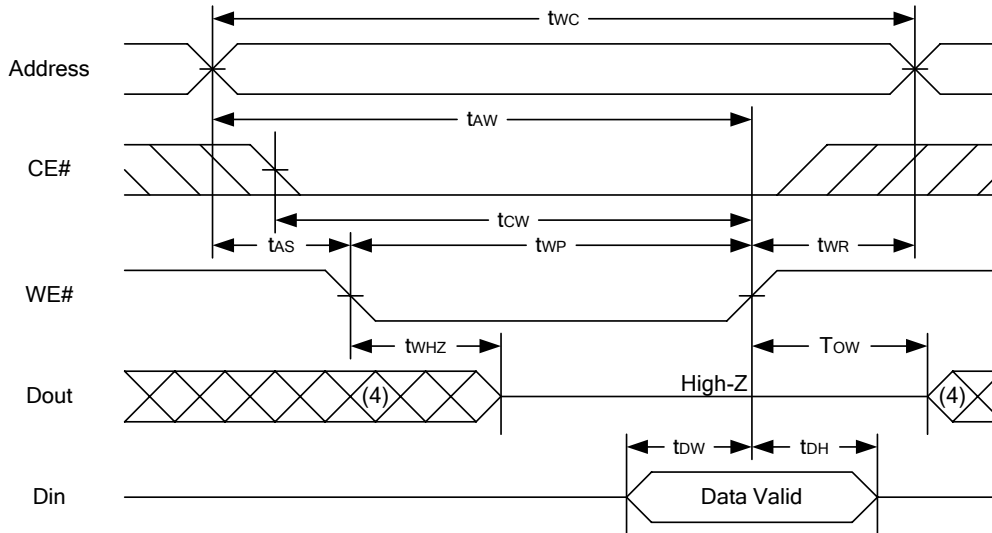
4. 25μA for special request

*C=Commercial temperature/I = Industrial temperature

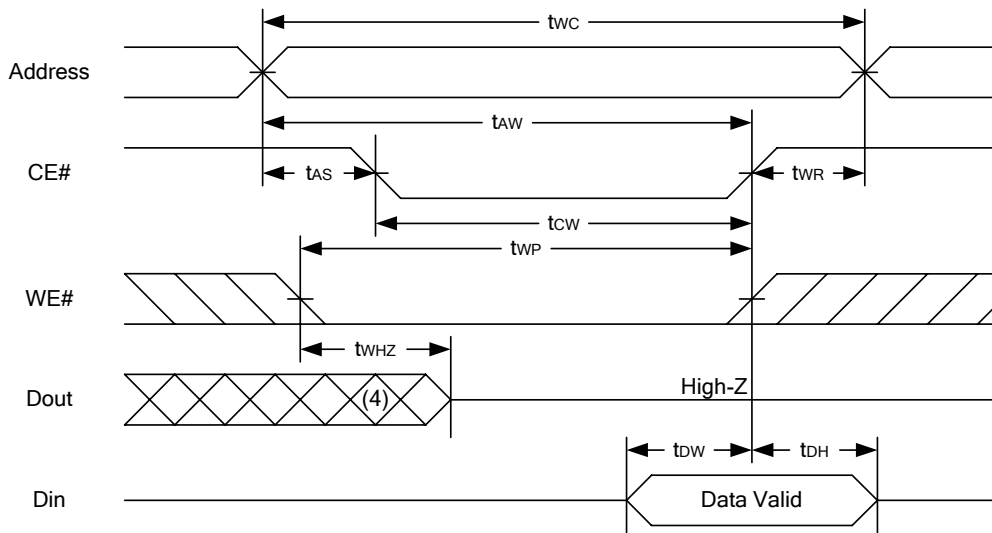


512K X 8 BIT LOW POWER CMOS SRAM

WRITE CYCLE 1 (WE# Controlled) (1,2,3,5,6)



WRITE CYCLE 2 (CE# Controlled) (1,2,5,6)



Notes :

1. WE#, CE# must be high during all address transitions.
2. A write occurs during the overlap of a low CE#, low WE#.
3. During a WE# controlled write cycle with OE# low, twp must be greater than twhz + tdw to allow the drivers to turn off and data to be placed on the bus.
4. During this period, I/O pins are in the output state, and input signals must not be applied.
5. If the CE# low transition occurs simultaneously with or after WE# low transition, the outputs remain in a high impedance state.
6. tow and twhz are specified with CL = 5pF. Transition is measured ±500mV from steady state.

Rev. 1.1

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Notes:

1. $V_{IH}(\max) = V_{CC} + 3.0V$ for pulse width less than 10ns.
2. $V_{IL}(\min) = V_{SS} - 3.0V$ for pulse width less than 10ns.
3. Over/Undershoot specifications are characterized, not 100% tested.
4. Typical values are included for reference only and are not guaranteed or tested.
Typical values are measured at $V_{CC} = V_{CC}(\text{TYP.})$ and $T_A = 25^\circ$

CAPACITANCE ($T_A = 25^\circ\text{C}$, $f = 1.0\text{MHz}$)

PARAMETER	SYMBOL	MIN.	MAX	UNIT
Input Capacitance	C_{IN}	-	6	pF
Input/Output Capacitance	$C_{I/O}$	-	8	pF

Note : These parameters are guaranteed by device characterization, but not production tested.

AC TEST CONDITIONS

Input Pulse Levels	0.2V to $V_{CC} - 0.2V$
Input Rise and Fall Times	3ns
Input and Output Timing Reference Levels	1.5V
Output Load	$C_L = 30\text{pF} + 1\text{TTL}$, $I_{OH}/I_{OL} = -1\text{mA}/2\text{mA}$

AC ELECTRICAL CHARACTERISTICS**(1) READ CYCLE**

PARAMETER	SYM.			AS6C4008-55				UNIT
		MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	
Read Cycle Time	t_{RC}			55	-			ns
Address Access Time	t_{AA}			-	55			ns
Chip Enable Access Time	t_{ACE}			-	55			ns
Output Enable Access Time	t_{OE}			-	30			ns
Chip Enable to Output in Low-Z	t_{CLZ}^*			10	-			ns
Output Enable to Output in Low-Z	t_{OLZ}^*			5	-			ns
Chip Disable to Output in High-Z	t_{CHZ}^*			-	20			ns
Output Disable to Output in High-Z	t_{OHZ}^*			-	20			ns
Output Hold from Address Change	t_{OH}			10	-			ns

(2) WRITE CYCLE

PARAMETER	SYM.			AS6C4008-55				UNIT
		MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	
Write Cycle Time	t_{WC}			55	-			ns
Address Valid to End of Write	t_{AW}			50	-			ns
Chip Enable to End of Write	t_{CW}			50	-			ns
Address Set-up Time	t_{AS}			0	-			ns
Write Pulse Width	t_{WP}			45	-			ns
Write Recovery Time	t_{WR}			0	-			ns
Data to Write Time Overlap	t_{DW}			25	-			ns
Data Hold from End of Write Time	t_{DH}			0	-			ns
Output Active from End of Write	t_{OW}^*			5	-			ns
Write to Output in High-Z	t_{WHZ}^*			-	20			ns

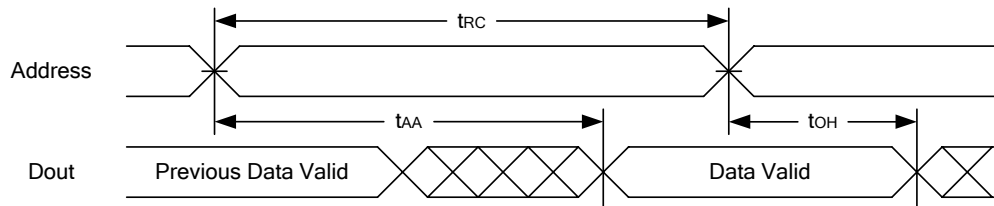
*These parameters are guaranteed by device characterization, but not production tested.



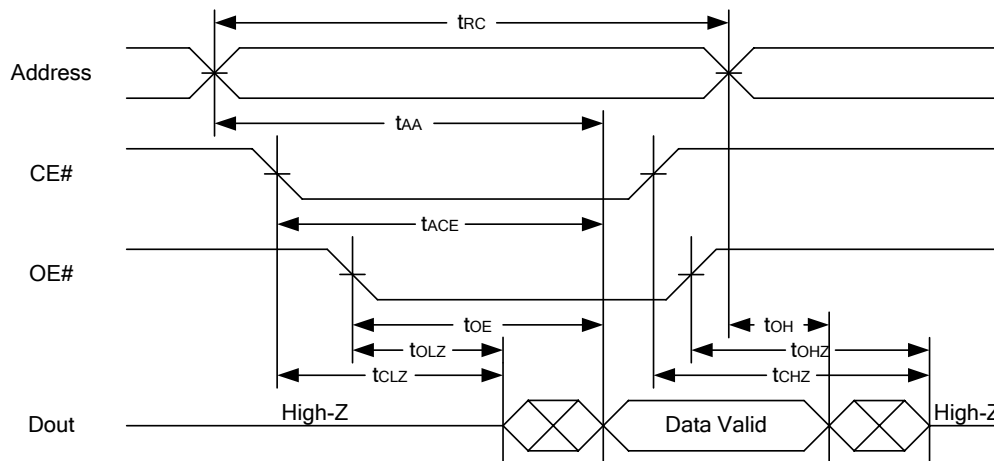
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TIMING WAVEFORMS

READ CYCLE 1 (Address Controlled) (1,2)



READ CYCLE 2 (CE# and OE# Controlled) (1,3,4,5)



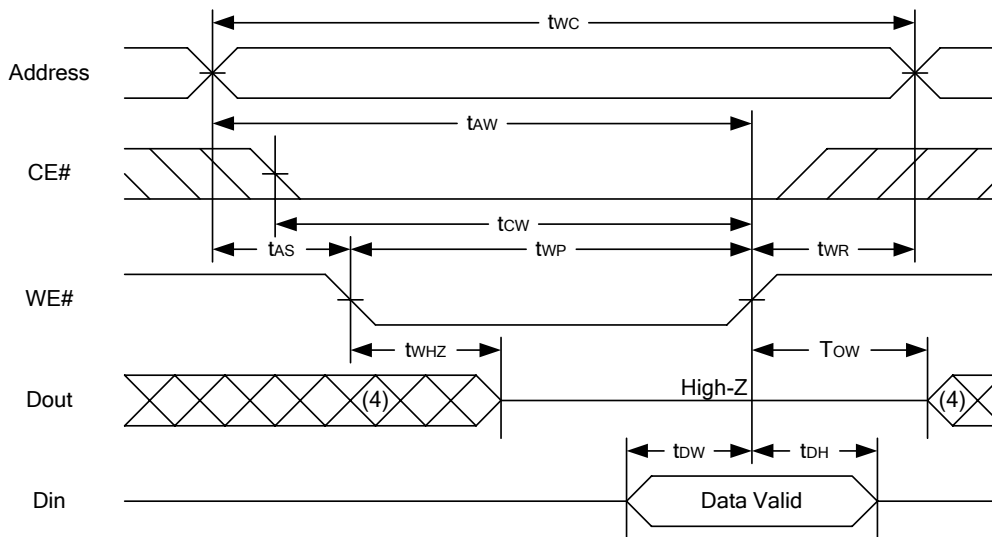
Notes :

1. WE# is high for read cycle.
2. Device is continuously selected OE# = low, CE# = low.
3. Address must be valid prior to or coincident with CE# = low.; otherwise tAA is the limiting parameter.
4. tCLZ, tOLZ, tCHZ and tOHZ are specified with CL = 5pF. Transition is measured ±500mV from steady state.
5. At any given temperature and voltage condition, tCHZ is less than tCLZ, tOHZ is less than tOLZ.

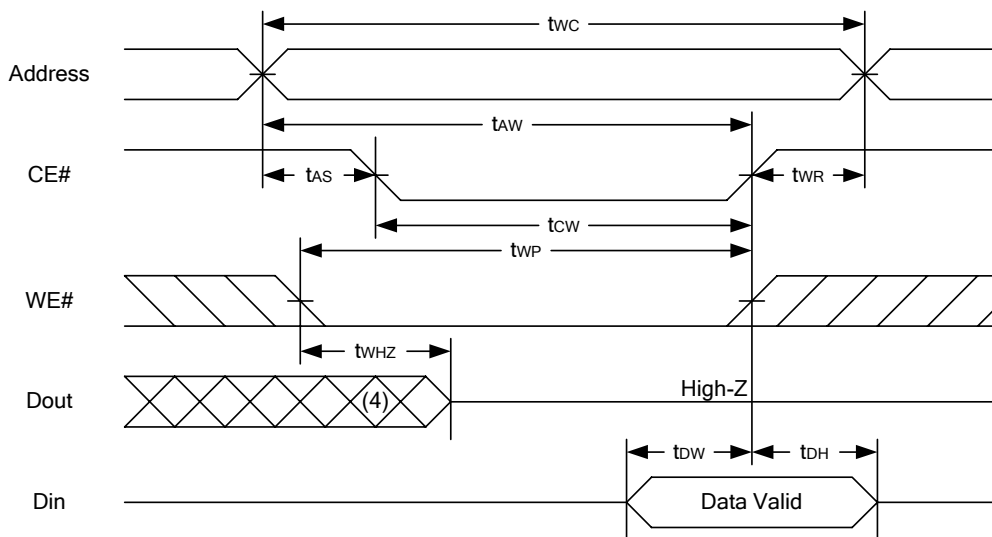


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WRITE CYCLE 1 (WE# Controlled) (1,2,3,5,6)



WRITE CYCLE 2 (CE# Controlled) (1,2,5,6)



Notes :

1. WE#, CE# must be high during all address transitions.
2. A write occurs during the overlap of a low CE#, low WE#.
3. During a WE# controlled write cycle with OE# low, twp must be greater than twhz + tdw to allow the drivers to turn off and data to be placed on the bus.
4. During this period, I/O pins are in the output state, and input signals must not be applied.
5. If the CE# low transition occurs simultaneously with or after WE# low transition, the outputs remain in a high impedance state.
6. tdw and twhz are specified with CL = 5pF. Transition is measured ±500mV from steady state.

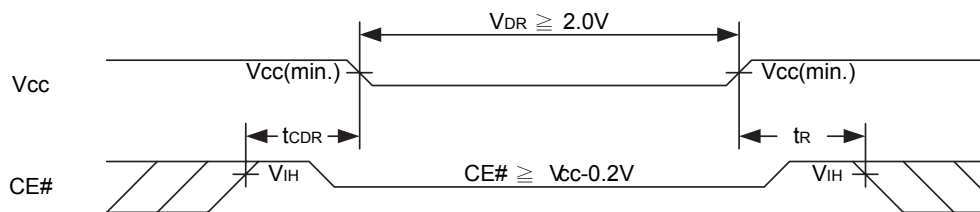


512K X 8 BIT LOW POWER CMOS SRAM

DATA RETENTION CHARACTERISTICS

PARAMETER	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
V _{CC} for Data Retention	V _{DR}	CE# ≥ V _{CC} - 0.2V	2.0	-	5.5	V
Data Retention Current	I _{DR}	V _{CC} = 2.0V	-	2	30	μ
		CE# ≥ V _{CC} - 0.2V	-	2	30	μA
Chip Disable to Data Retention Time	t _{CDR}	See Data Retention Waveforms (below)	0	-	-	ns
Recovery Time	t _R		t _{RC} *	-	-	ns

t_{RC}* = Read Cycle Time **C=Commercial temperature/I=Industrial temperature

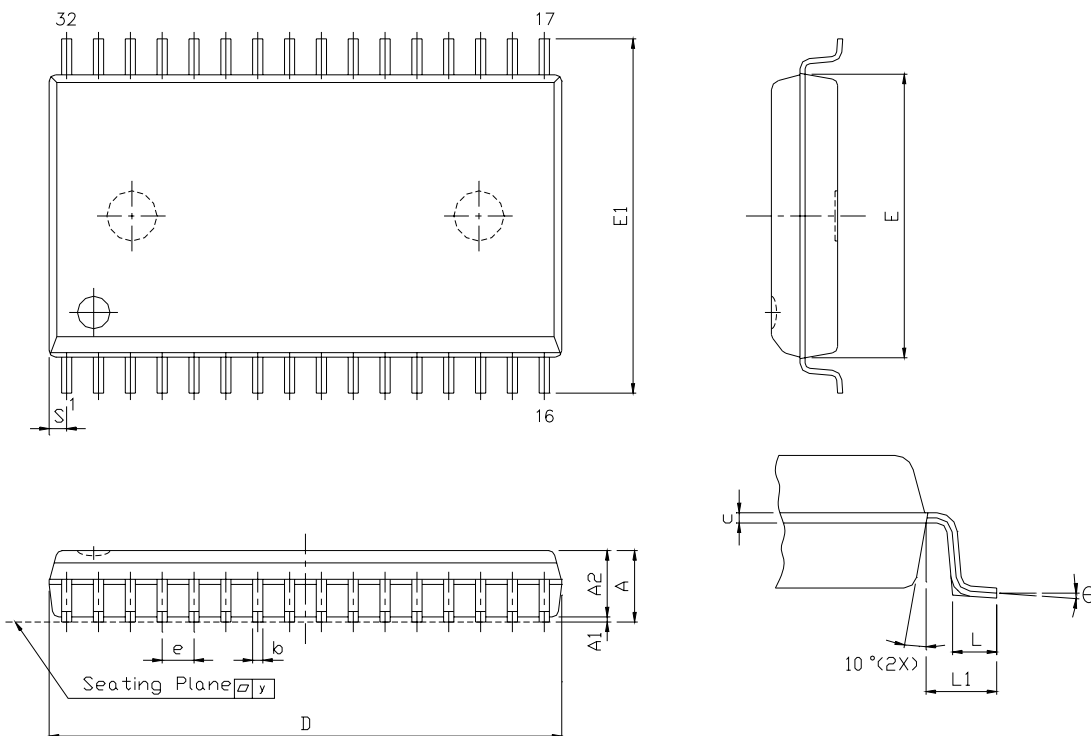
DATA RETENTION WAVEFORM



512K X 8 BIT LOW POWER CMOS SRAM

PACKAGE OUTLINE DIMENSION

32 pin 450 mil SOP Package Outline Dimension

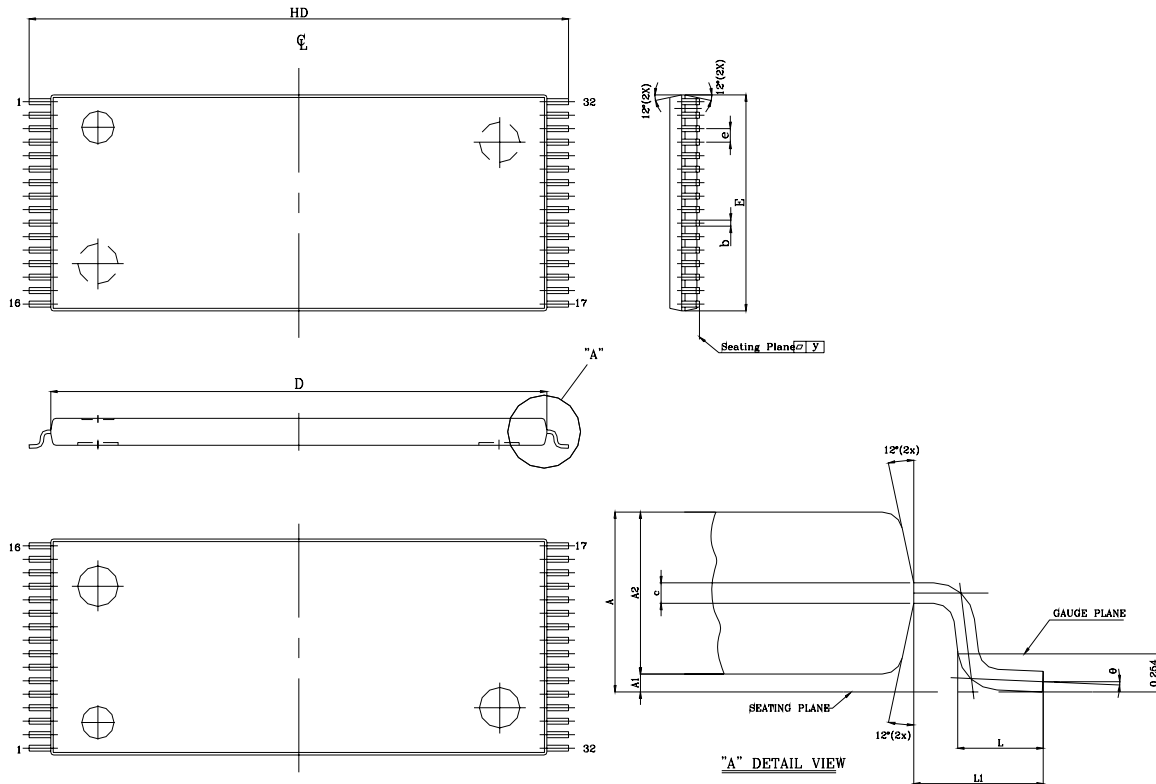


SYM.	UNIT	INCH.(BASE)	MM(REF)
A		0.118 (MAX)	2.997 (MAX)
A1		0.004(MIN)	0.102(MIN)
A2		0.111(MAX)	2.82(MAX)
b		0.016(TYP)	0.406(TYP)
c		0.008(TYP)	0.203(TYP)
D		0.817(MAX)	20.75(MAX)
E		0.445 ±0.005	11.303 ±0.127
E1		0.555 ±0.012	14.097 ±0.305
e		0.050(TYP)	1.270(TYP)
L		0.0347 ±0.008	0.881 ±0.203
L1		0.055 ±0.008	1.397 ±0.203
S		0.026(MAX)	0.660 (MAX)
y		0.004(MAX)	0.101(MAX)
Θ		0° -10°	0° -10°



512K X 8 BIT LOW POWER CMOS SRAM

32 pin 8mm x 20mm TSOP-I Package Outline Dimension

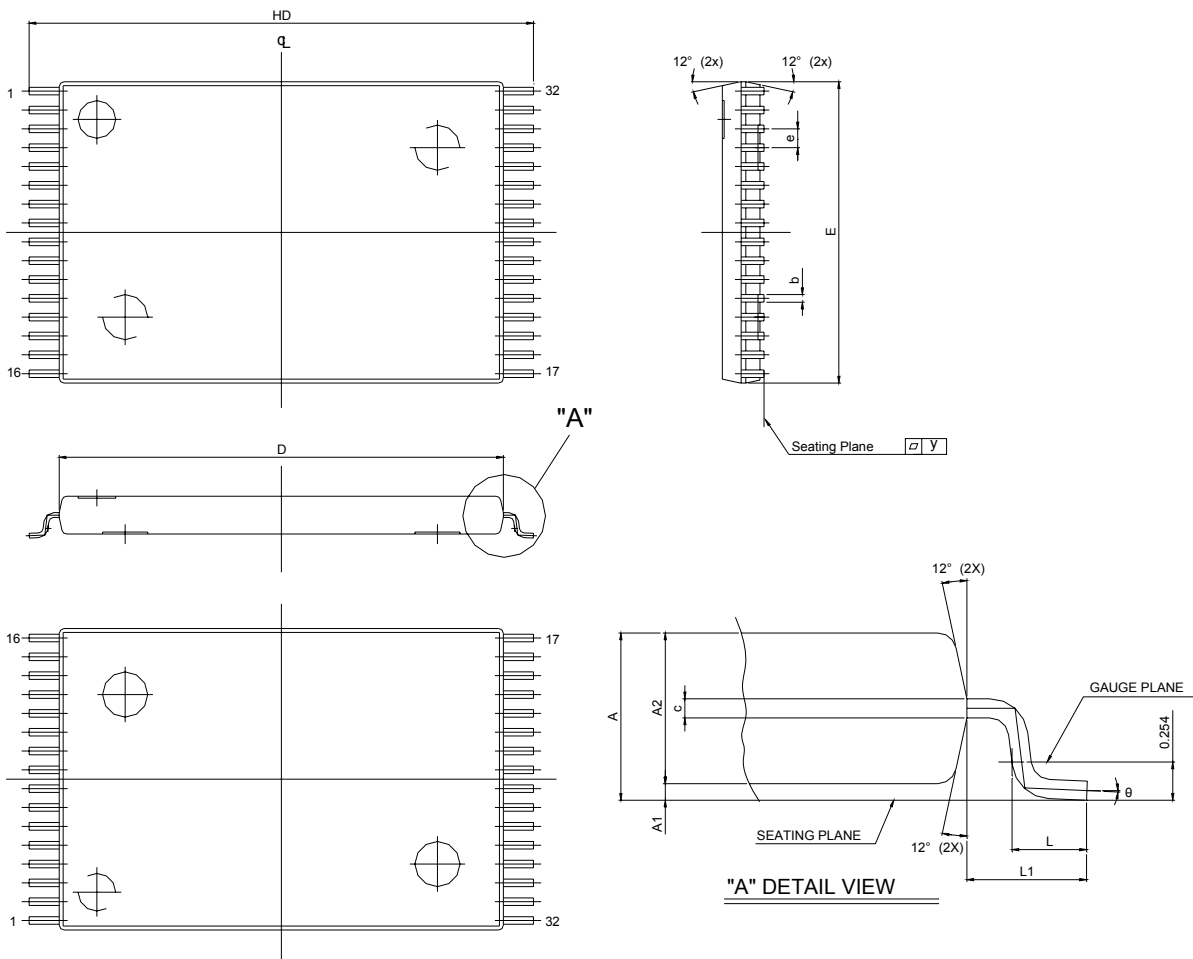


SYM.	UNIT	INCH(BASE)	MM(REF)
A		0.047 (MAX)	1.20 (MAX)
A1		0.004 ±0.002	0.10 ±0.05
A2		0.039 ±0.002	1.00 ±0.05
b		0.008 + 0.002 - 0.001	0.20 + 0.05 - 0.03
c		0.005 (TYP)	0.127 (TYP)
D		0.724 ±0.004	18.40 ±0.10
E		0.315 ±0.004	8.00 ±0.10
e		0.020 (TYP)	0.50 (TYP)
HD		0.787 ±0.008	20.00 ±0.20
L		0.0197 ±0.004	0.50 ±0.10
L1		0.0315 ±0.004	0.08 ±0.10
y		0.003 (MAX)	0.076 (MAX)
θ		0°~5°	0°~5°



512K X 8 BIT LOW POWER CMOS SRAM

32 pin 8mm x 13.4mm sTSP Package Outline Dimension

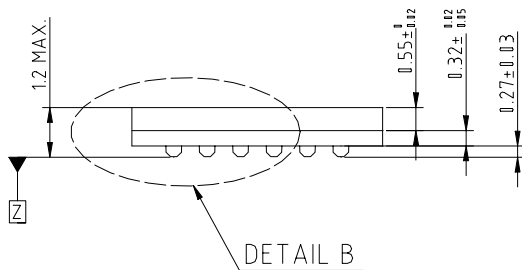
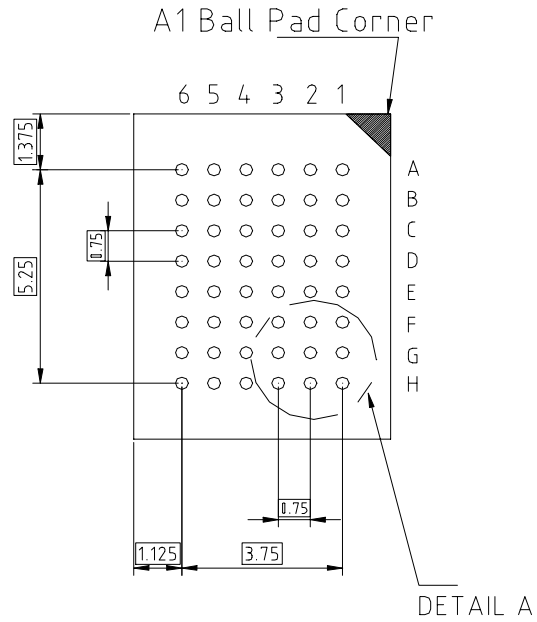
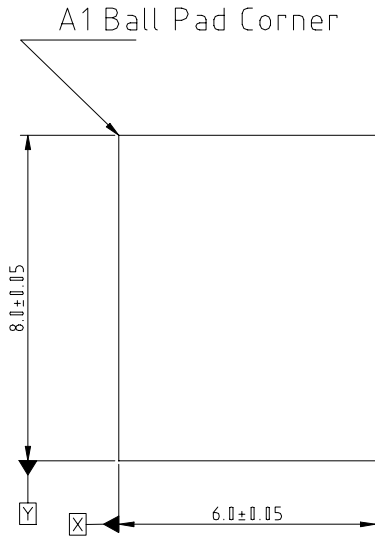


SYM.	UNIT	INCH(BASE)	MM(REF)
A		0.049 (MAX)	1.25 (MAX)
A1		0.005 ±0.002	0.130 ±0.05
A2		0.039 ±0.002	1.00 ±0.05
b		0.008 ±0.01	0.20±0.025
c		0.005 (TYP)	0.127 (TYP)
D		0.465 ±0.004	11.80 ±0.10
E		0.315 ±0.004	8.00 ±0.10
e		0.020 (TYP)	0.50 (TYP)
HD		0.528±0.008	13.40 ±0.20.
L		0.0197 ±0.004	0.50 ±0.10
L1		0.0315 ±0.004	0.8 ±0.10
y		0.003 (MAX)	0.076 (MAX)
θ		0°~5°	0°~5°

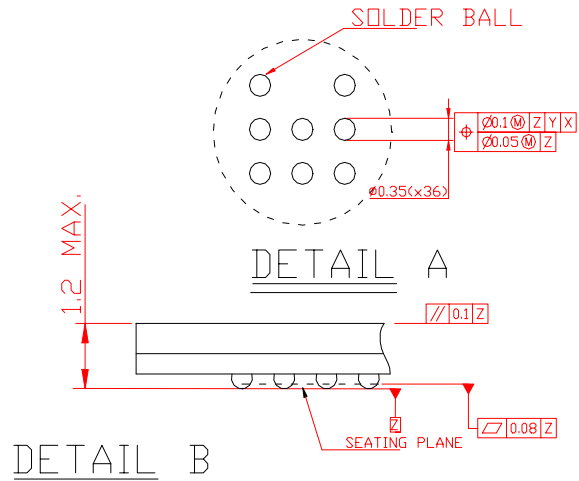


512K X 8 BIT LOW POWER CMOS SRAM

36 ball 6mm x 8mm TFBGA Package Outline Dimension



SIDE VIEW

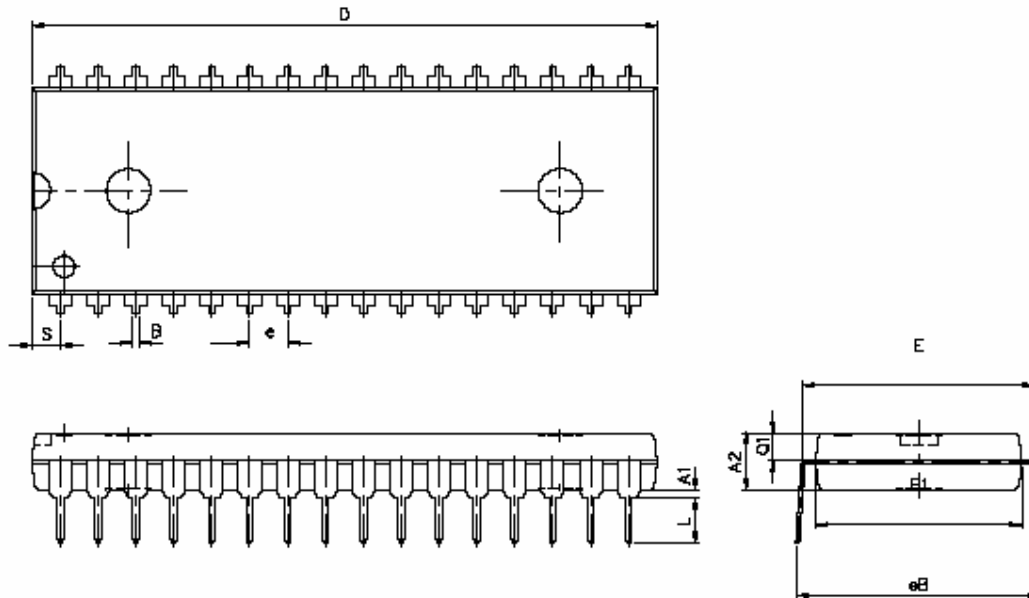


DETAIL B



512K X 8 BIT LOW POWER CMOS SRAM

32 pin 600 mil P-DIP Package Outline Dimension



SYM.	UNIT	INCH(BASE)	MM(REF)
A1		0.001 (MIN)	0.254 (MIN)
A2		0.150 ± 0.005	3.810 ± 0.127
B		0.018 ± 0.005	0.457 ± 0.127
D		1.650 ± 0.005	41.910 ± 0.127
E		0.600 ± 0.010	15.240 ± 0.254
E1		0.544 ± 0.004	13.818 ± 0.102
e		0.100 (TYP)	2.540 (TYP)
eB		0.640 ± 0.020	16.256 ± 0.508.
L		0.130 ± 0.010	3.302 ± 0.254
S		0.075 ± 0.010	1.905 ± 0.254
Q1		0.070 ± 0.005	1.778 ± 0.127

Note : D/E1/S dimension do not include mold flash.



512K X 8 BIT LOW POWER CMOS SRAM

ORDERING INFORMATION

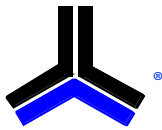
Ordering Codes

Alliance	Organization	VCC range	Package	Operating Temp	Speed ns
AS6C4008-55PCN	512k x 8	2.7-5.5V	32pin 600mil PDIP	Commercial ~ 0° C to 70° C	55
AS6C4008-55SIN	512k x 8	2.7-5.5V	32pin 450mil SOP	Industrial ~ -40° C to 85° C	55
AS6C4008-55TIN	512k x 8	2.7-5.5V	32pin TSOP-I (8 x 20 mm)	Industrial ~ -40° C to 85° C	55
AS6C4008-55STIN	512k x 8	2.7-5.5V	32pin sT SOP (8 x 13.4 mm)	Industrial ~ -40° C to 85° C	55
AS6C4008-55BIN	512k x 8	2.7-5.5V	36pin TFBGA (6mm x 8mm) *	Industrial ~ -40° C to 85° C	55
			*Coming Soon!		

Part numbering system

AS6C	4008	- 55	X	X	N
low power SRAM prefix	Device Number 40 = 4M 08 = by 8	Access Time	Package Options: P = 32 pin 600 mil P-DIP S = 32 pin 450 mil SOP T = 32 pin TSOP-I (8mm x 20 mm) ST = 32 pin sT SOP (8mm x 13.4 mm) B = 36 pin TFBGA (6mm x 8mm) *	Temperature Range: C = Commercial (0° C to +70° C) I = Industrial (-40° to +85° C)	N = Lead Free ROHS Compliant Part

* Coming Soon!



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